

Description

The DFS15HF12DEA1 is 34mm package SiC power module. It offers lower losses and higher energy for applications such as motor drives, inverter, UPS and welding applications.



Features

- 1200V/15m Ω
- High Frequency Operation
- Si₃N₄ AMB substrate
- Fast intrinsic diode with low reverse recovery

Applications

- Motor drives
- Inverter
- UPS
- Welding application

Circuit diagram

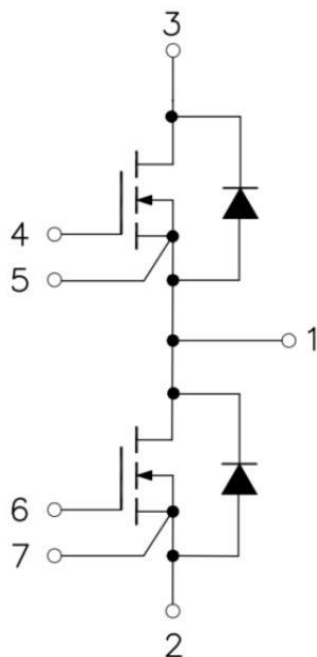


Figure 1. Out drawing & circuit diagram for DFS15HF12DEA1

Pin Configuration and Marking Information

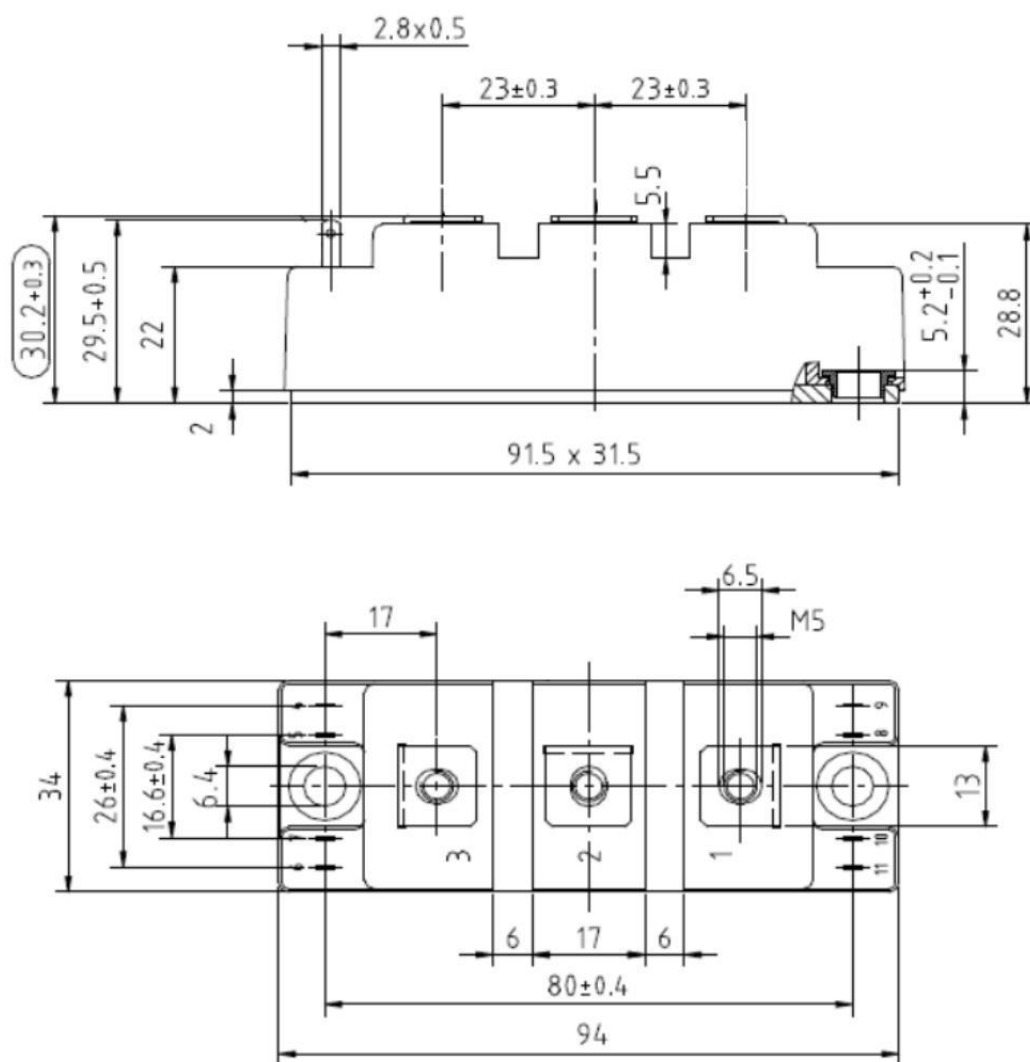


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, f= 50Hz, t =1min	2.5	kV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	26	mm
		21	
Clearance	terminal to heatsink terminal to terminal	23.6	mm
		10	
CTI	-	>200	-

Module lead resistance, terminals - chip	T _C =25°C	0.8	mΩ
Mounting torque for module mounting	M5, M6	3 to 6	Nm
Weight	-	160	g

Maximum Ratings (SiC MOSFET, $T_j = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DS}	Drain-Source Voltage	G-S Short	1200	V
V_{GS}	Gate-Source Voltage	D-S Short, AC frequency $\geq 1\text{Hz}$, Note1	-10 to 23	V
I_{DS}	DC Continuous Drain Current	$T_c = 25^\circ\text{C}$, $V_{GS} = 18\text{V}$	126	A
		$T_c = 100^\circ\text{C}$, $V_{GS} = 18\text{V}$	90	A
I_{SD}	Source-Drain Current(diode)	$T_c = 25^\circ\text{C}$, with ON signal	126	A
		$T_c = 100^\circ\text{C}$, with ON signal	90	A
I_{DSM}	Pulse Drain Current	$T_c = 25^\circ\text{C}$, Pulse width = 1ms, $V_{GS} = 18\text{V}$, Note2	340	A
P_{tot}	Total Power Dissipation	$T_c = 25^\circ\text{C}$	893	W
T_{jmax}	Max Junction Temperature	-	175	$^\circ\text{C}$
T_{stg}	Storage Temperature	-	-55 to 175	$^\circ\text{C}$

Note1: Recommended Operating Value, +18V/-4V

Note2: Pulse width limited by maximum junction temperature

SiC MOSFET Electrical characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =100μA		1200	-	-	V
V _{GS(th)}	Gate-source threshold Voltage	I _D =27mA, V _{DS} =V _{GS}	T _j =25°C	2.0	2.8	3.7	V
			T _j =150°C	-	2.1	-	
			T _j =175°C	-	2.0	-	
I _{DSS}	Zero gate voltage drain Current	V _{DS} =1200V, V _{GS} =0V	T _j =25°C	0	1	50	μA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =18V, V _{DS} =0V	T _j =25°C	0	1	200	nA
R _{DS(on)} (Chip)	Static drain-source On-state resistance	I _D =80A V _{GS} =+18V	T _j =25°C	-	15	18	mΩ
			T _j =150°C	-	25	-	
			T _j =175°C	-	28	-	
V _{DS(on)} (Chip)	Static drain-source On-state Voltage	I _D =80A V _{GS} =+18V	T _j =25°C	-	1.89	-	V
			T _j =150°C		3.15		
			T _j =175°C	-	3.53	-	

C_{iss}	Input Capacitance	$V_D=1000V, V_{GS}=0V$ $f=1MHz, V_{AC}=25mV$	-	4.3	-	nF
C_{oss}	Output Capacitance		-	0.214	-	
C_{rss}	Reverse transfer Capacitance		-	0.019	-	
R_{Gint}	Internal gate resistor	$f=1MHz, I_D=0V$	-	1.4	-	Ω
Q_g	Total gate charge	$V_{DD}=800V, I_D=80A, V_{GS}=+18/-4V$	-	222	-	nC
Q_{gs}	Gate-source charge		-	55	-	
Q_{gd}	Gate-drain charge		-	88	-	
$R_{th(j-c)}$	FET Thermal Resistance	Junction to Case, Note1	-	0.168	-	$^{\circ}C/W$

Note1: Assumes Thermal Conductivity of grease is $2.8 W/m \cdot K$ and thickness is 50um.

Body Diode Electrical characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified, chip: Target)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{SD}	Body Diode Forward Voltage	V _{GS} =-4V, I _{SD} =40A	T _j =25°C	-	4.1	-	V
			T _j =150°C	-	3.7	-	
			T _j =175°C	-	3.6	-	
I _S	Continuous Diode Forward Current	V _{GS} = -4V	T _j =25°C	-	-	97	A
T _{rr}	Reverse recovery time	V _{DD} =800V, I _D =80A V _{GS} =+18/-4V, R _g =1Ω Inductive load	T _j =25°C	-	21	-	ns
Q _{rr}	Reverse recovery charge		T _j =25°C	-	470	-	nC
I _{rr}	Diode switching power dissipation		switching operation	T _j =25°C	-	40	-

Test Conditions

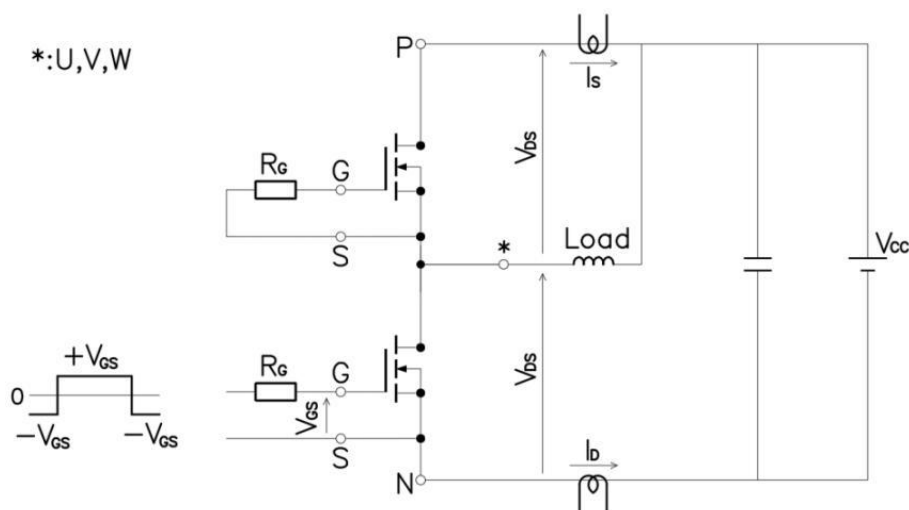


Figure 3. Switching time measure circuit

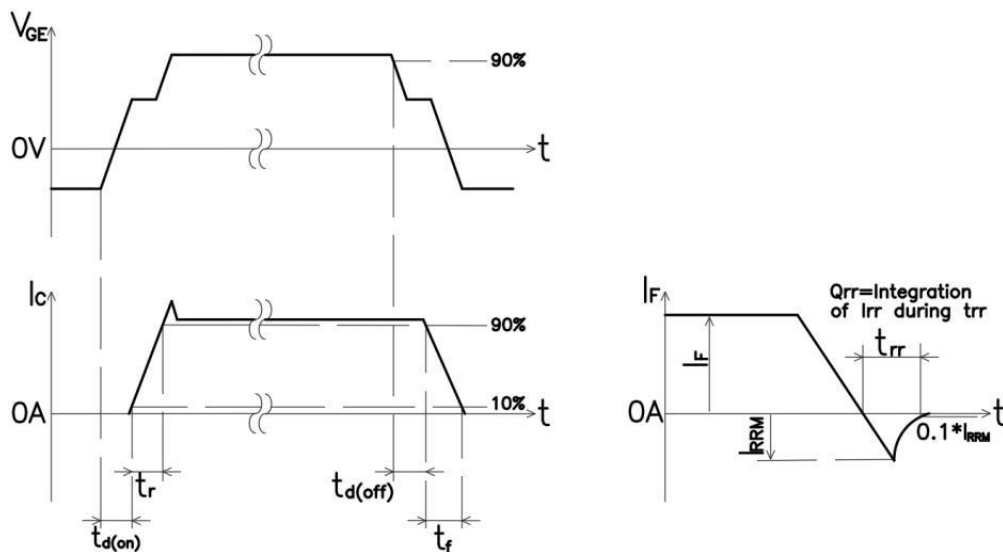


Figure 4. Switching time definition

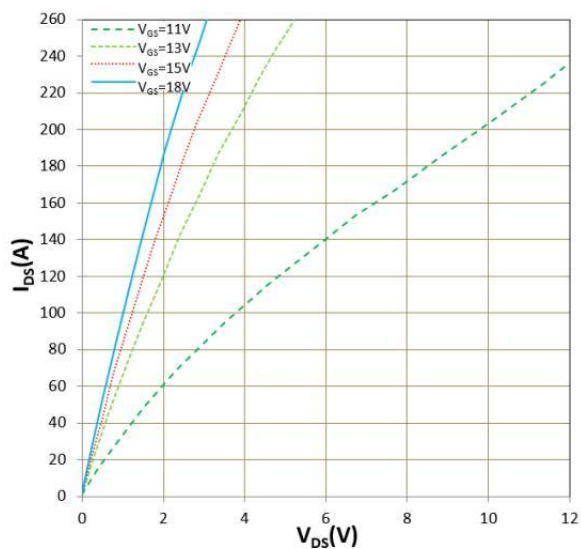


Figure 5. I_{DS} vs V_{DS}
 $T_j = 25^\circ\text{C}$

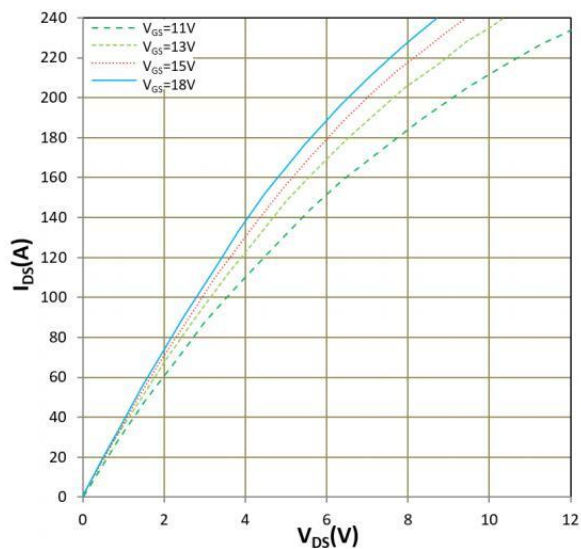


Figure 6. I_{DS} vs V_{DS}
 $T_j = 175^\circ\text{C}$

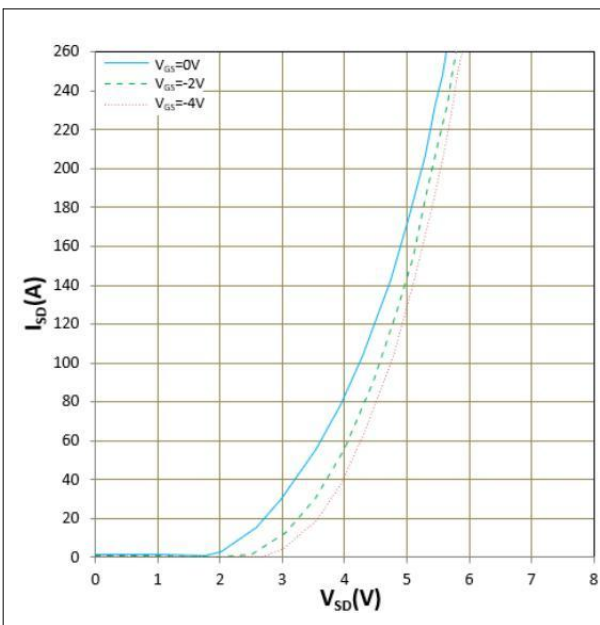


Figure 7. I_{SD} vs V_{SD}
 $T_J = 25^\circ\text{C}$

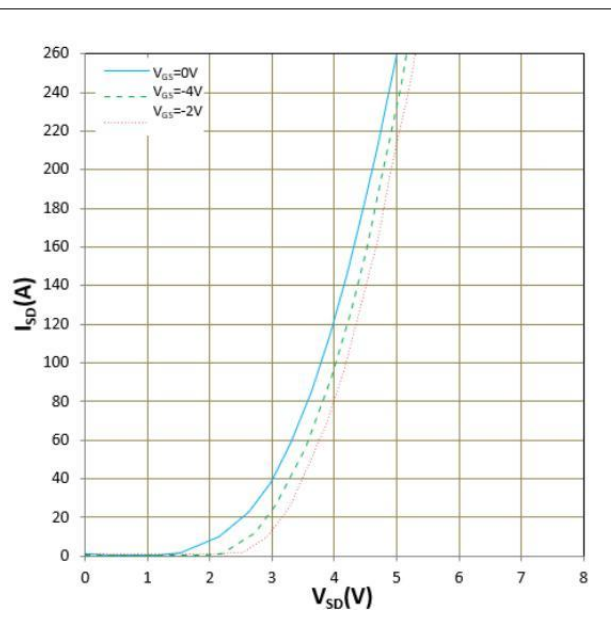


Figure 8. I_{SD} vs V_{SD}
 $T_J = 175^\circ\text{C}$

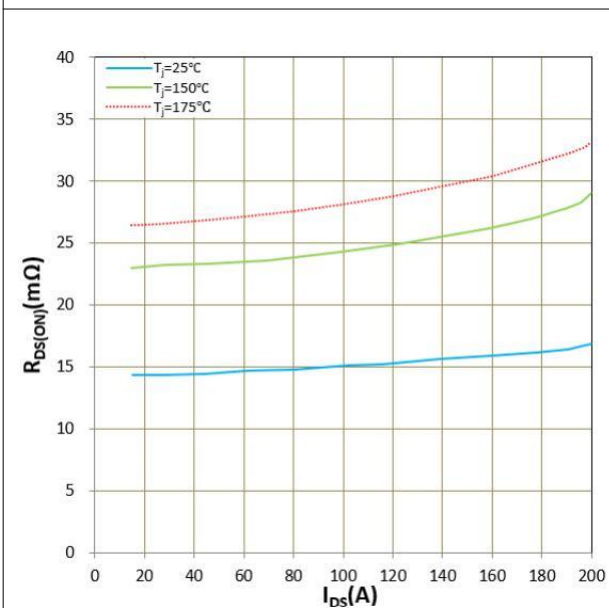


Figure 9. $R_{DS(ON)}$ vs I_{DS}

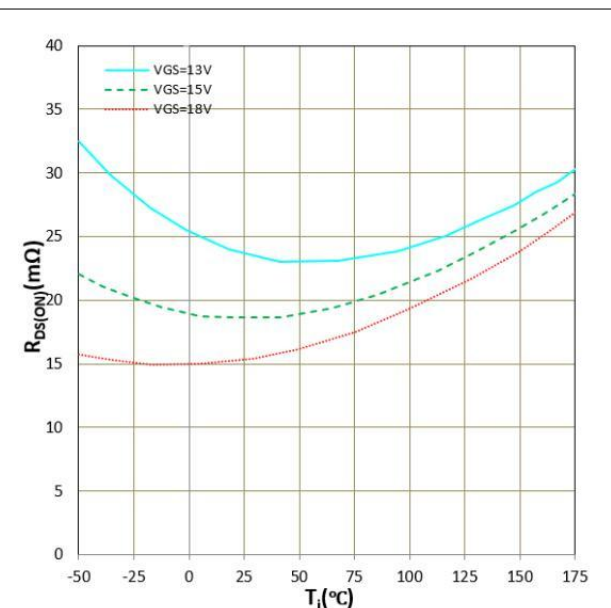


Figure 10. $R_{DS(ON)}$ vs T_J
 $I_{DS} = 80\text{A}$

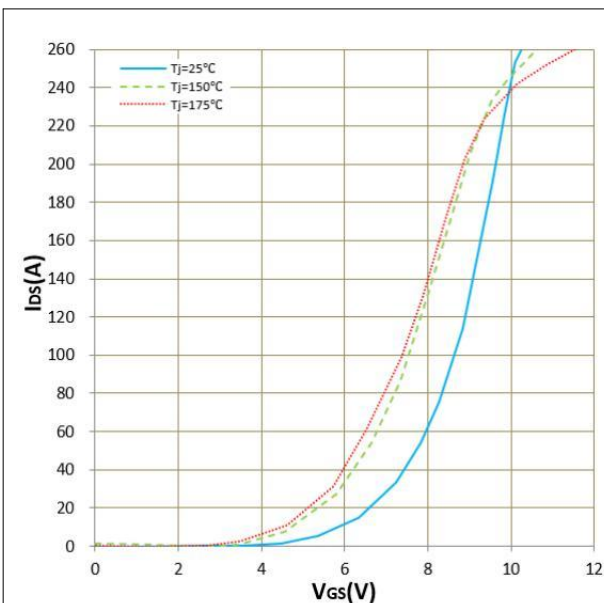


Figure 11. I_{DS} vs V_{GS}
 $V_{DS}=20V$

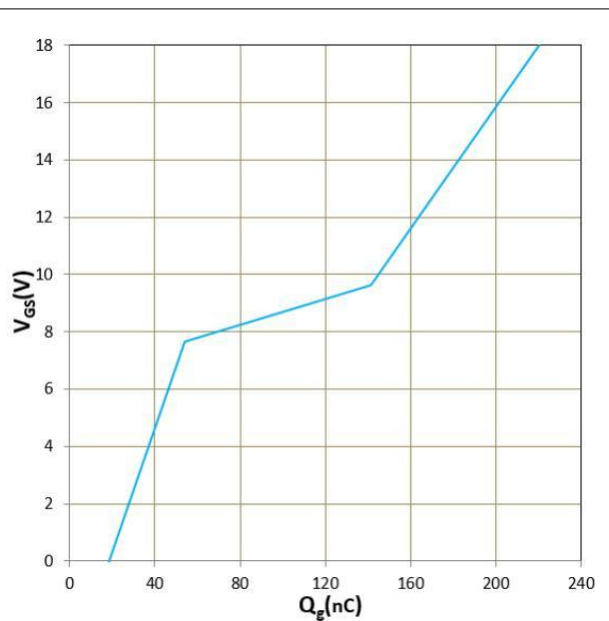


Figure 12. Gate charge
 $V_{DS}=800V$, $I_{DS}=80A$, $I_{GS}=1mA$, $T_J=25^{\circ}C$

Preliminary datasheet_Ver.A EN

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